



CIPAL-Compass®: Copper-Induced Pitting in Aluminium Alloys - Modeling, Life Prediction and Process Control

Version 9.20

☆ Performance ☆ Functionality ☆ Usability



Anytime	Anywhere	Any Device	Any OS No USB
dongles	No installation	No Browser Plug-ins	
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Why WebCorr | Performance Guarantee | Unparalleled Functionality | Unmatched Usability | Any Device Any OS | Free Training & Support | CorrCompass

Features and Component of CIPAL-Compass

CIPAL-Compass is the only device and OS independent software on the market for the modeling and life prediction of copper-induced pitting in aluminium alloys used in the microelectronics and

semiconductor industry, the chemical process industry, the power generation industry, the water treatment industry, and any industry/sector where aluminium alloys come into contact with waters or process fluids that contain trace amount of copper ions. Designers, engineers, architects, consultants, maintenance and inspection personnel can quickly assess and quantify the impact of copper ions on the pitting corrosion of aluminum alloys, the pit depth, the pitting rate, the remaining life of their components or systems, and the critical level of copper ions for process control. CIPAL-Compass utilizes machine learning and cloud computing and works anytime, anywhere, on any device running any OS without the need to install or download anything.

CIPAL-Compass consists of two modules:

- Copper-Induced Pitting in Aluminium Alloys module is used for modeling and life prediction of aluminum alloys in contact with trace amount of copper ions in waters and process fluids.
- Intermetallics module is used for modeling and life prediction of intermetallics-induced pitting in aluminium alloys.

Overview and Application Examples of CIPAL-Compass for Modeling and Life Prediction of Aluminum Alloys

Figures below show the screen shots of CIPAL-Compass. CIPAL-Compass quantitatively determines the effect of the chemistry of water or process fluid on the pitting corrosion of aluminum alloys: temperature, pH, conductivity, sulphate, chloride, and copper ions. The outputs from CIPAL-Compass includes the pit depth, the pitting rate, the predicted life span, and the remaining life of the component.

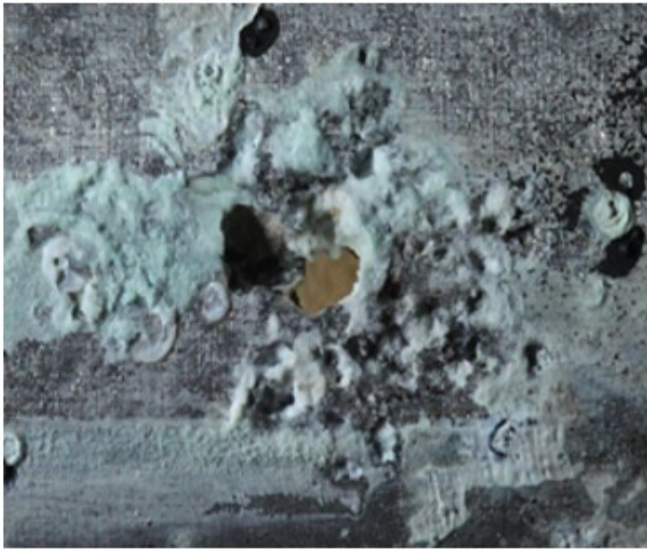
CIPAL-Compass®: Copper-Induced Pitting in Aluminium Alloys					
AA1XXX		Part ID/System: AA6061 Tube/PCW1/Campus A			
Age of Part	years	1.000			
Thickness of Part	mm	2.850			
Temperature	°C	90.000			
pH	pH	7.400			
Conductivity	µS/cm	131.000			
Sulphate [SO ₄ ²⁻]	mg/L	2.650			
Chloride [Cl ⁻]	mg/L	8.260			
Copper [Cu ²⁺]	mg/L	0.200			
Area Ratio (A _{Cu} /A _{pit})	A _{Cu} /A _{pit}	1.000			
Pit Depth	mm	1.184	Pitting Rate	mm/y	1.184
Remaining Life	years	1.407	Predicted Life Span	years	2.407

Figure 1 Overview of CIPAL-Compass

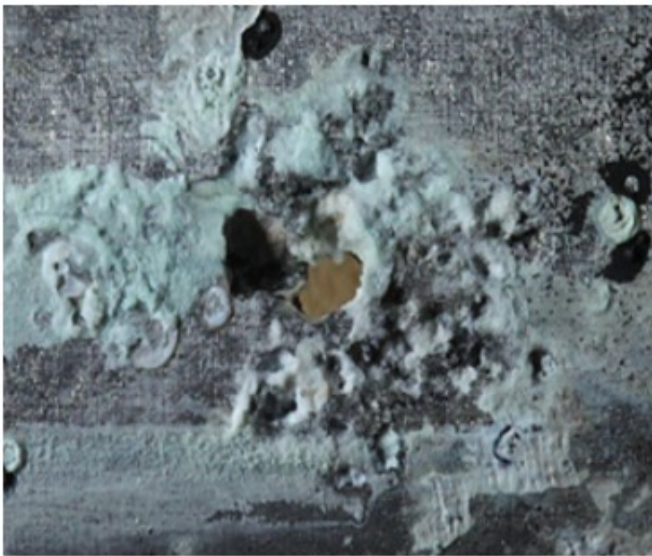
CIPAL-Compass®: Copper-Induced Pitting in Aluminium Alloys					
AA1XXX	▼	Part ID/System: AA6061 Tube/PCW1/Campus A			
AA1XXX	years	1.000			
AA2XXX	mm	2.850			
AA3XXX	°C	90.000			
AA5XXX	pH	7.400			
AA6XXX					
AA7XXX					
Conductivity	μS/cm	131.000			
Sulphate [SO ₄ ²⁻]	mg/L	2.650			
Chloride [Cl ⁻]	mg/L	8.260			
Copper [Cu ²⁺]	mg/L	0.200			
Area Ratio (A _{Cu} /A _{pit})	A _{Cu} /A _{pit}	1.000			
Pit Depth	mm	1.184	Pitting Rate	mm/y	1.184
Remaining Life	years	1.407	Predicted Life Span	years	2.407

Figure 2 Selection of Aluminium Alloys Series in CIPAL-Compass

Users of CIPAL-Compass start by selecting the aluminum alloy series from the dropdown list. The specific grade of aluminium alloy in a particular series is not required as all grades within the same series showed similar corrosion behaviour.

After selecting the aluminium alloys series, the next step is to enter the chemistry parameters of the water or process fluid. Temperature, pH, conductivity and concentrations of sulphate, chloride, and copper ions are all critical factors that influences both the initiation of pitting and the propagation rate of pitting in aluminum alloys.

CIPAL-Compass also models the galvanic effect of copper deposition on the aluminium surface by

taking into account of the surface area ratio of the copper deposit to the pit opening.

Service Life Prediction for Process Piping in Semiconductor Manufacturing

In semiconductor manufacturing, the process cooling water is frequently contaminated with copper ions, which will deposit on aluminium alloy AA6061 piping surface and induce pitting corrosion in aluminum alloy AA6061. The temperature of process cooling water is about 90°C and the pipe wall thickness is 2.85 mm. The chemistry of the process water is as entered. CIPAL-Compass predicts that the piping would leak in about 2.5 years after operation due to copper-induced pitting in the aluminum alloy.

CIPAL
Intermetallics

CIPAL-Compass®: Copper-Induced Pitting in Aluminium Alloys

AA6XXX

▼

Part ID/System: AA6061 Tube/PCW1/Campus A

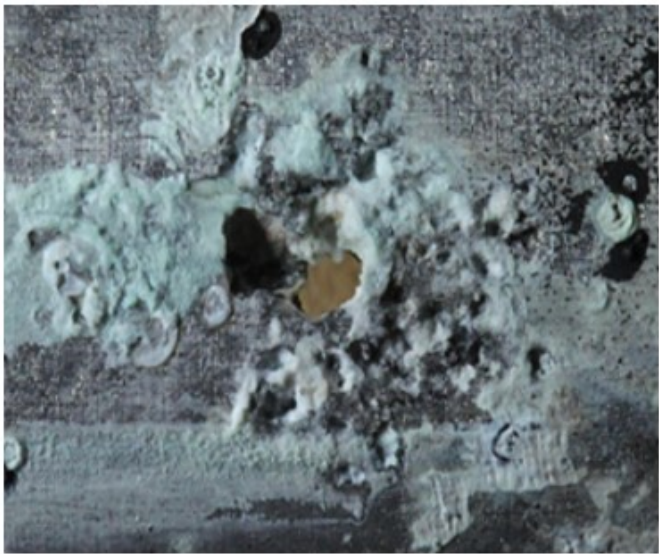
Age of Part	years	1.000			
Thickness of Part	mm	2.850			
Temperature	°C	90.000			
pH	pH	7.400			
Conductivity	µS/cm	131.000			
Sulphate [SO ₄ ²⁻]	mg/L	2.650			
Chloride [Cl ⁻]	mg/L	8.260			
Copper [Cu ²⁺]	mg/L	0.300			
Area Ratio (A _{Cu} /A _{pit})	A _{Cu} /A _{pit}	1.000			
Pit Depth	mm	1.226	Pitting Rate	mm/y	1.226
Remaining Life	years	1.325	Predicted Life Span	years	2.325

Figure 3 Service Life Prediction for Process Piping in Semiconductor Manufacturing

Overview of CIPAL-Compass for Intermetallics-Induced Pitting in Aluminum Alloys

Intermetallics, their size and distribution in aluminium alloys, are critical factors influencing the alloys' mechanical strength and corrosion resistance properties. Some intermetallics are anodic to the aluminum matrix while others are cathodic to the matrix. The anodic intermetallics will corrode preferentially, creating cavities/holes in the aluminium matrix (Figure 4). The cathodic intermetallics will not corrode themselves but causing corrosion of the matrix around their perimeters (Figure 5). Figures below show overviews of the CIPAL-Compass module for Intermetallics-Induced Pitting in Aluminum Alloys.

CIPAL

Intermetallics

Corrosion of Intermetallics in Aluminium Alloys

The predicted potential difference is with respect to the alloy matrix (α -Al)

Select the Intermetallic: Mg₂Si

Conductivity, μ S/cm: 131

Operating Temperature, $^{\circ}$ C: 25.00

Potential Difference at 25 $^{\circ}$ C, mV: -97

Galvanic Position of Intermetallic: anodic to the matrix

IM Induced Pitting Rate, nm/h: 16 μ m/y: 143

Expected Pit Morphology: Intermetallics selectively dissolve, forming deep pits in the matrix.

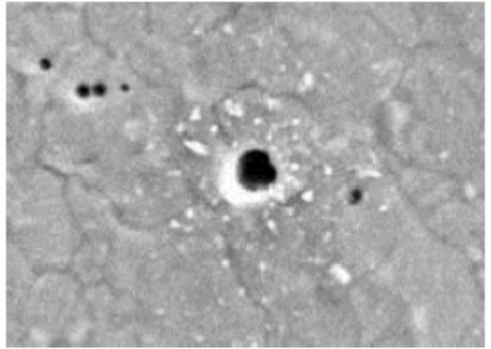


Figure 4 Overview of CIPAL-Compass for Intermetallics-Induced Pitting in Aluminum Alloys

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Corrosion of Intermetallics in Aluminium Alloys	
<i>The predicted potential difference is with respect to the alloy matrix (α-Al)</i>	
Select the Intermetallic:	Al7Cu2Fe
Conductivity, $\mu\text{S}/\text{cm}$:	131
Operating Temperature, $^{\circ}\text{C}$:	25.00
Potential Difference at 25°C , mV:	691
Galvanic Position of Intermetallic:	cathodic to the matrix
IM Induced Pitting Rate, nm/h:	16
	$\mu\text{m}/\text{y}$: 143
Expected Pit Morphology: Circumferential pits, with attack in the matrix around isolated IM particles.	

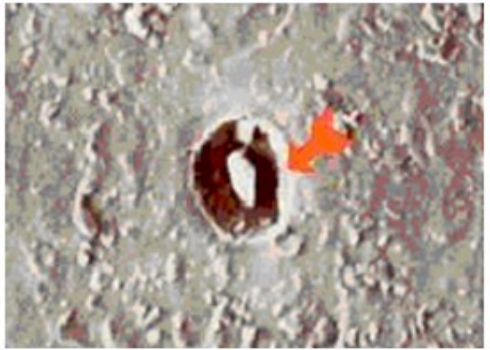


Figure 5 Overview of CIPAL-Compass for Intermetallics-Induced Pitting in Aluminium Alloys

A dozen of intermetallics commonly found in aluminium alloys are available for selection in CIPAL-Compass (Figure 6). If you cannot find the intermetallics of your interest in the list, do let us know through the [Contact Us link](#) and we will conduct the necessary tests to generate the required data for inclusion in the software.

Reset AlSiMgZr
 Mg_2Si
 MgZn_2

- Predicted potential difference (at 25°C) with respect to the alloy matrix (α -Al). The greater the potential difference, the greater the galvanic effect between the IM particles and the matrix.
- The galvanic position of the selected intermetallic with respect to the alloy matrix. The intermetallic can be anodic to the matrix or cathodic to the matrix, depending on the composition of the intermetallic.

- The intermetallic-induced pitting rate in nano-meter per hour (nm/h), and micro-meter per year ($\mu\text{m/y}$).
- The expected pit morphology. For intermetallics anodic to the matrix, the intermetallics themselves will be preferentially dissolved, leading to the formation of deep pits in the alloy matrix (see Figure 4 above). For intermetallics cathodic to the matrix, the intermetallics act as cathodes in the corrosion process and they are not subject to corrosion. However, the matrix is the anode in the corrosion process and corrodes around the isolated IM particles, leading to the formation of circumferential pits with the IM particles remain in the center (see Figure 5 above). Eventually, the IM particles will fall out of the pit holes.

WebCorr can customize CIPAL-Compass for your specific process fluids and alloys used in any industry from general engineering to wafer fabrication.

CIPAL-Compass, giving you the right directions in Pitting Prediction in Aluminum Alloys

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